



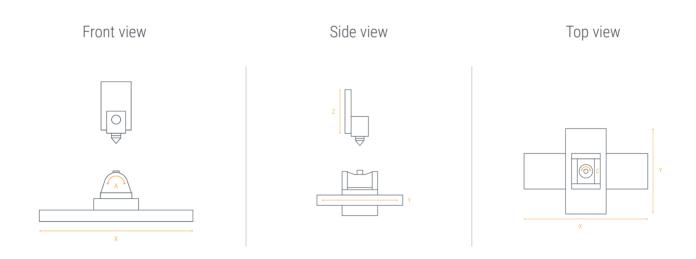
The industrial laser microprocessing system GL. compact is designed for applications that require less high dynamics than a reliable positioning of the workpiece for further processing by scanner or spiral drilling optics.

The machine is characterized by a very compact design and high flexibility. Thanks to the use of state-of-the-art beam sources and the possibility to integrate all available hardware options, the complete spectrum of laser microprocessing can be served.

HIGHLIGHTS

- reasonably-priced entry into high-precision ultrashort pulse laser processing
- optimal accessibility for automation
- glass scales
- linear motors

- working area 490 x 280 [mm]
- small set-up area (< 3,5 sqm)
- weight-optimized design (< 3 to)
- 3+2 axis machining
- 5-axis simultaneous machining possible for fixed application



TECHNICAL DATA

Axis	Χ	Υ	Z	В	С
Axis type	linear			rotary	
Drive type	direct drive		spindle drive	torque drive	
Bearing	profile rail guide		M&V-guidance	roller bearing	
Travels [mm]	490	280	340	+/- 90°	endless
Speed	30 m/min		60 m/min	700 U/min	
Acceleration	5 m/s²		20 m/s ²	160 1/s²	220 1/s²
Repeatability			3 μm	10 arcsec	
Accuracy			4 μm	20 arcsec	
Perm. comp. weight	< 20 kg			0,5 kg	
Clamping set-up	drilling pattern			clamping system	
Sound pressure level	≤ 70 dB				
Dimensions [mm]	B = 1400 / T = 2600 / H = 2650				
Total weight	3000 kg without supply and without control cabinet				